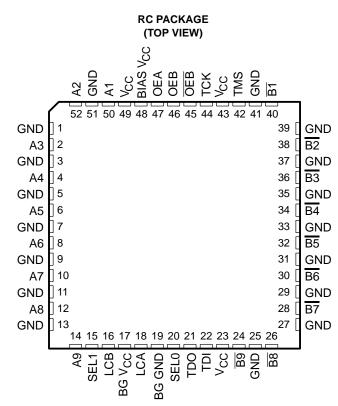
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- Compatible With IEEE Std 1194.1-1991 (BTL)
- TTL A Port, Backplane Transceiver Logic (BTL) B Port
- Open-Collector B-Port Outputs Sink 100 mA
- High-Impedance State During Power Up and Power Down
- BIAS V_{CC} Minimizes Signal Distortion During Live Insertion or Withdrawal
- B-Port Biasing Network Preconditions the Connector and PC Trace to the BTL High-Level Voltage
- TTL-Input Structures Incorporate Active Clamping to Aid in Line Termination



description

The SN74FB2031 is a 9-bit transceiver designed to translate signals between TTL and backplane transceiver logic (BTL) environments. The device is designed specifically to be compatible with IEEE Std 1194.1-1991.

The \overline{B} port operates at BTL-signal levels. The open-collector \overline{B} ports are specified to sink 100 mA. Two output enables (OEB and \overline{OEB}) are provided for the \overline{B} outputs. When OEB is low, \overline{OEB} is high, or V_{CC} is less than 2.1 V, the \overline{B} port is turned off.

The A port operates at TTL signal levels. The A outputs reflect the inverse of the data at the \overline{B} port when the A-port output enable (OEA) is high. When OEA is low or V_{CC} is less than 2.1 V, the A outputs are in the high-impedance state.

Pins are allocated for the four-wire IEEE Std 1149.1 (JTAG) test bus, although currently there are no plans to release a JTAG-featured version. TMS and TCK are not connected and TDI is shorted to TDO.



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description (continued)

BIAS V_{CC} establishes a voltage between 1.62 V and 2.1 V on the BTL outputs when V_{CC} is not connected.

BG $V_{\mbox{CC}}$ and BG GND are the supply inputs for the bias generator.

ORDERING INFORMATION

TA	PACKAGET		···-	TOP-SIDE MARKING	
0°C to 70°C	QFP – RC	Tube	SN74FB2031RC	FB2031	

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Function Tables

TRANSCEIVER

	INPUTS		FUNCTION				
OEA	OEB	OEB	FUNCTION				
L	Н	L	A data to B bus				
н	L	Х					
н	Х	Н	B data to A bus				
Н	Н	L	\overline{A} data to B bus, \overline{B} data to A bus				
L	L	Х	Isolation				
L	Х	Н	isuation				

STORAGE MODE

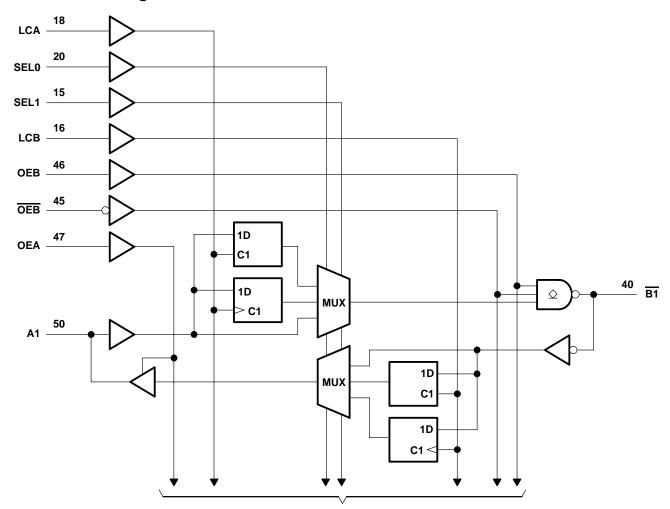
LCA, LCB	RESULT
0	Transparent
1	Latches latched
↑	Flip-flops triggered

SEL	_ECT	

SEL1	SEL0	MUX A→B	MUX B→A
0	0	Latch	Latch
0	1	Through	Through
1	0	Flip-flop	Flip-flop
1	1	Flip-flop	Latch



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functional block diagram

To Eight Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I : Except B port B port Voltage range applied to any B output in the disabled or power-off state, V _O Voltage range applied to any output in the high state, V _O Input clamp current, I _{IK} : Except B port B port Current applied to any single output in the low state, I _O : A port	
Package thermal impedance, θ_{JA} (see Note 1) Storage temperature range, T_{sta}	200 mA 44°C/W

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 2)

			MIN	NOM	MAX	UNIT
V _{CC} , BIAS V _{CC} , BG V _{CC}	Supply voltage		4.5	5	5.5	V
Maria	B port		1.62		2.3	V
VIH	High-level input voltage	Except B port	2			v
Mu	Low lovel input veltage	B port			1.47	V
VIL	Low-level input voltage	Except B port			0.8	v
ЮН	High-level output current	A port			-3	mA
	Low lovel output ourrest	A port			24	mA
IOL	Low-level output current B port				100	ША
Т _А	Operating free-air temperature		0		70	°C

NOTE 2: To ensure proper device operation, all unused inputs must be terminated as follows: A and control inputs to V_{CC}(5 V) or GND, and B inputs to GND only. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST	CONDITIONS	MIN	түр†	MAX	UNIT
Ver	B port	$V_{CC} = 4.5 V,$	lj = -18 mA			-1.2	V
VIK	Except B port	$V_{CC} = 4.5 V,$	l _l = –40 mA			-0.5	v
VOH	A port	$V_{CC} = 4.5 V,$	I _{OH} = -3 mA	2.5	3.3		V
	A port	$V_{CC} = 4.5 V,$	I _{OL} = 24 mA		0.35	0.5	
VOL	-	V _{CC} = 4.5 V	I _{OL} = 80 mA	0.75		1.1	V
	B port	VCC = 4.5 V	I _{OL} = 100 mA			1.15	
lj	Except B port	V _{CC} = 5.5 V,	V _I = 5.5 V			50	μA
Iн‡	Except B port	V _{CC} = 5.5 V,	V _I = 2.7 V			50	μA
. +	Except B port	V _{CC} = 5.5 V,	V _I = 0.5 V			-50	
IIL‡	B port	V _{CC} = 5.5 V,	V _I = 0.75 V			-100	μA
IOZH	A port	$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V},$	V _O = 2.7 V			50	μA
I _{OZL}	A port	V _{CC} = 2.1 V to 5.5 V,	V _O = 0.5 V			-50	μA
IOZPU	A port	$V_{CC} = 0$ to 2.1 V,	V_{O} = 0.5 V to 2.7 V			50	μA
IOZPD	A port	V _{CC} = 2.1 V to 0,	V_{O} = 0.5 V to 2.7 V			-50	μΑ
ЮН	B port	$V_{CC} = 0$ to 5.5 V,	V _O = 2.1 V			100	μA
los§	A port	V _{CC} = 5.5 V,	VO = 0	-30		-150	mA
	A port to B port					78	
ICC	B port to A port	V _{CC} = 5.5 V,	IO = 0	78		78	mA
Ci	-	V _I = 0.5 V or 2.5 V			4.5		pF
	A port	V _O = 0.5 V or 2.5 V			8.5		
Cio	B port per IEEE Std 1194.1-1991	V _{CC} = 0 to 5.5 V				6	pF

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

 \ddagger For I/O ports, the parameters IIH and IIL include the off-state output current.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.



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live-insertion specifications over recommended operating free-air temperature range

PAR	AMETER	TEST CONDITIONS				MAX	UNIT
$V_{CC} = V_{CC}$		$V_{CC} = 0$ to 4.5 V				450	μA
СС (ы		V_{CC} = 4.5 V to 5.5 V	$V_{\rm B} = 0$ to 2 V,	V_{I} (BIAS V_{CC}) = 4.5 V to 5.5 V		10	μΑ
Vo	B port	$V_{CC} = 0,$	V_{I} (BIAS V_{CC}) = 5 V		1.62	2.1	V
		$V_{CC} = 0,$	V _B = 1 V,	V_I (BIAS V_{CC}) = 4.5 V to 5.5 V	-1		
IO	B port	$V_{CC} = 0$ to 5.5 V,	OEB = 0 to 0.8 V			100	μΑ
		$V_{CC} = 0$ to 2.2 V,	OEB = 0 to 5 V			100	

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				MIN	MAX	UNIT
fclock	Clock frequency				150	MHz
tw	Pulse duration	LCA or LCB		3.3		ns
		Clock mode	Data before LCA↑	1.4		
	Setup time	Clock mode	Data before LCB↑	2.8		
^t su	Setup time	Latch mode	Data before LCA↑	1.1		ns
			Data before LCB↑	2.4		
		Clock mode	Data after LCA↑	0.6		
+.	Hold time	CIUCK MODe	Data after LCB↑	0		-
th		Data after LCA↑	0.9		ns	
		Laten mode	Data after LCB↑	0		



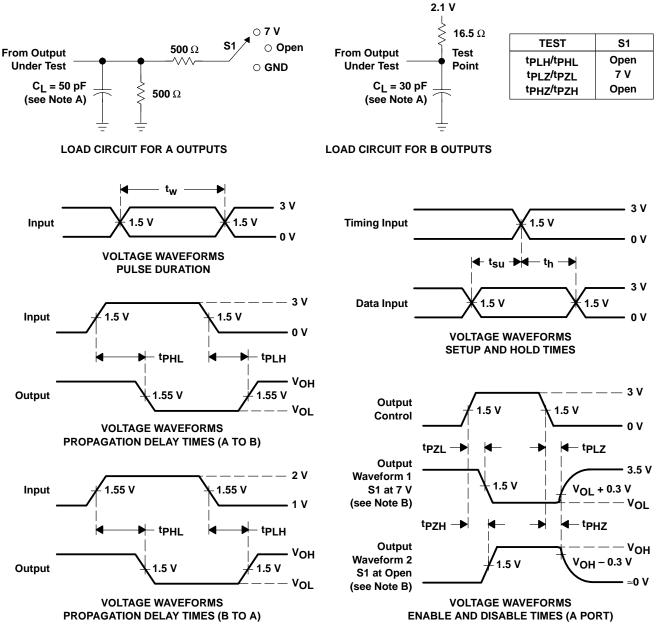
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C T	CC = 5 \ A = 25°C	/, C	MIN	МАХ	UNIT
		(001201)	MIN	TYP	MAX			
f _{max}			150			150		MHz
^t PLH	А	B	3.7	4.5	5.9	3.2	6.6	
^t PHL	(through mode)	В	2.9	4	5.7	2.6	5.9	ns
^t PLH	А	B	4.1	5	6.5	3.6	7.3	ns
^t PHL	(transparent)	В	3.3	4.5	6.1	3	6.5	115
^t PLH	LCA	B	4.5	5.4	7	3.9	7.8	ns
^t PHL	LUA	В	4	5.1	6.7	3.4	7.4	115
^t PLH	LCB	А	2.8	3.7	4.7	1.9	6	ns
^t PHL	LCB	A	2.5	3.4	4.9	1.8	5.5	115
^t PLH	SEL1 or SEL0	А	2.5	3.8	5.3	1.9	6.3	200
^t PHL	SELT OF SELO	~	2.2	3.5	5.1	1.6	5.6	ns
^t PLH	SEL1 or SEL0	B	4.1	5.3	6.9	3.7	7.8	
^t PHL	SELT OF SELU	В	3.7	5.2	6.9	3.3	7.7	ns
^t PLH	B	А	3.1	4	5.6	2.2	7.1	ns
^t PHL	(through mode)	A	2.6	3.4	4.9	1.4	5.7	
^t PLH	B	А	3.3	4.2	5.9	2.4	7.6	
^t PHL	(transparent)	A	2.8	3.9	5.5	1.8	6.3	ns
^t PLH		B	3.7	4.6	6.1	3.2	6.7	
^t PHL	OEB or OEB	В	2.9	4.3	5.8	2.5	6.4	ns
^t PZH	OEA	А	2.3	3.1	4.5	1.6	5	ns
^t PZL	OEA	A	1.9	2.7	4.1	1.6	4.4	115
^t PHZ	OEA	٨	2.2	3.1	4.5	1.5	5.2	
^t PLZ	UEA	A	2.5	3.3	4.9	2	5.2	ns
	A	В		0.5				
^t sk(p) Pulse skew	B	А		0.3				ns
^t sk(o)	A	В		0.2				
Output skew	B			0.3				ns
	Transition time, B outputs (1.3	V to 1.8 V)	0.6	2	2.8	0.4	2.9	
t _t		Transition time, A outputs (1.3 v to 1.5 v)			4.7	0	5.4	ns
^t (pr)	B-port input pulse rejection					1		ns



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: TTL inputs: PRR ≤ 10 MHz, Z_Q = 50 Ω, t_r ≤ 2.5 ns,
 - $t_f \le 2.5 \text{ ns}$; BTL inputs: PRR $\le 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_f \le 2.5 \text{ ns}$, $t_f \le 2.5 \text{ ns}$.

D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74FB2031RC	ACTIVE	QFP	RC	52	96	TBD	CU SNPB	Level-2-240C-1 YEAR
SN74FB2031RCG3	ACTIVE	QFP	RC	52	96	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR
SN74FB2031RCR	ACTIVE	QFP	RC	52	500	TBD	CU SNPB	Level-2-240C-1 YEAR
SN74FB2031RCRG3	ACTIVE	QFP	RC	52	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74FB2031 :

Military: SN54FB2031

NOTE: Qualified Version Definitions:

• Military - QML certified for Military and Defense Applications

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*/	Il dimensions are nominal												
	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	SN74FB2031RCR	QFP	RC	52	500	330.0	24.4	14.2	14.2	2.6	24.0	24.0	Q2
	SN74FB2031RCRG3	QFP	RC	52	500	330.0	24.4	14.2	14.2	2.6	24.0	24.0	Q2



PACKAGE MATERIALS INFORMATION

18-Sep-2008



*All dimensions are nominal

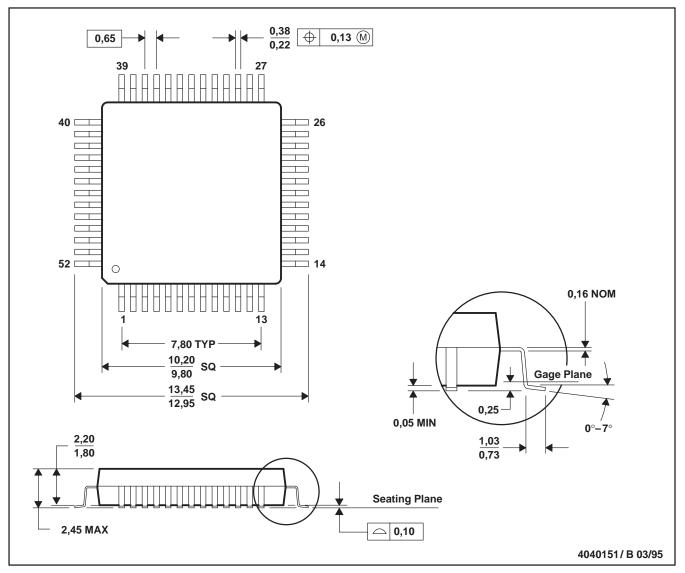
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74FB2031RCR	QFP	RC	52	500	346.0	346.0	41.0
SN74FB2031RCRG3	QFP	RC	52	500	346.0	346.0	41.0

MECHANICAL DATA

MQFP003 - OCTOBER 1994

RC (S-PQFP-G52)

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-022



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